



GE Energy

## Functional Testing Specification

Parts & Repair Services  
Louisville, KY

LOU-GED-531X126SNDAEG1

### Test Procedure for a 531X126SNDAEG1 snubber card

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LOU-GED-531X126SNDAEG1 REV. A	g  <b>GE Energy</b> Parts & Repair Services Louisville, KY	Page 2 of 3
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## 1. SCOPE

1.1 This is a functional testing procedure for a 531X126SNDAEG1 snubber card

## 2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

## 3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein.  
Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

## 4. ENGINEERING REQUIREMENTS

### 4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

### 4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold


4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

## 5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 or Equivalent

LOU-GED-531X126SND AEG1 REV. A	<div style="text-align: center;">   <b>GE Energy</b>  Parts &amp; Repair Services  Louisville, KY </div>	Page 3 of 3
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## 6. Modifications/Upgrades

6.1 Check Orange Book for any modifications or upgrades.

## 7. Testing Process

### 7.1 Testing Procedure

7.1.1 Using diode test on your multimeter make the following measurements to test the bridge rectifier.

7.1.1.1 (+) to CAC1, (-) to M = forward bias

7.1.1.2 (+) to CAC2, (-) to M = forward bias

7.1.1.3 (-) to CAC1, (+) to M = reverse bias

7.1.1.4 (-) to CAC2, (+) to M = reverse bias

7.1.1.5 (-) to CAC1, (+) to B = forward bias

7.1.1.6 (-) to CAC2, (+) to B = forward bias

7.1.1.7 (+) to CAC1, (-) to B = reverse bias

7.1.1.8 (+) to CAC2, (-) to B = reverse bias

7.1.2 Using a capacitance meter, test each the capacitors.

7.1.2.1 They should measure .22uf +/- 20%

7.1.3 Make the following resistance measurements. The resistance measurements should be measured from the side of the listed capacitor closest to the center of the card to the listed terminal.

7.1.3.1 C14 to P1 = 39 ohms +/- 5%

7.1.3.2 C16 to P1 = 39 ohms +/- 5%

7.1.3.3 C18 to P1 = 39 ohms +/- 5%

7.1.3.4 C13 to P2 = 39 ohms +/- 5%

7.1.3.5 C15 to P2 = 39 ohms +/- 5%

7.1.3.6 C17 to P2 = 39 ohms +/- 5%

7.1.4 Carefully inspect the card for any missing stab on connectors and for any broken solder connections.

### 7.2 \*\*\*TEST COMPLETE\*\*\*

## 8. Notes

8.1 None at this time.

## 9. Attachments

9.1 None at this time.